# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

Name	Execution Date
David S. Collins	10/09/2007
Mete Erturk	10/10/2007
Edward J. Gordon	10/10/2007
Robert Groves	10/09/2007
Robert M. Rassel	10/09/2007

### **RECEIVING PARTY DATA**

Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	New Orchard Road
City:	Armonk
State/Country:	NEW YORK
Postal Code:	10504

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11877155

# **CORRESPONDENCE DATA**

Fax Number: (513)241-6234

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Email: wallen@whepatent.com

Correspondent Name: William R. Allen
Address Line 1: 441 Vine Street
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Address Line 4: Cincinnati, OHIO 45202

ATTORNEY DOCKET NUMBER:	BUR920070072US2	
NAME OF SUBMITTER:	William R. Allen	

PATENT REEL: 020001 FRAME: 0662

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Total Attachments: 4 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif

> PATENT REEL: 020001 FRAME: 0663

# PATENT ASSIGNMENT FORM

For and in consideration of good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor acknowledges his/her prior and ongoing obligation to sell, assign, and transfer, and agrees to sell, assign, and transfer the entire world wide right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements conceived during and within the scope of his/her employment, and further acknowledges that he/she has sold, assigned, and transferred, and hereby sells, assigns, and transfers, unto:

# INTERNATIONAL BUSINESS MACHINES CORPORATION ("IBM"), Armonk, New York 10504

a corporation of New York, and IBM desires to acquire all right, title, and interest, in and to the certain inventions (identified below), applications, and any United States and foreign patents to be obtained therefor relating to:

Title of Invention for United States Patent DESIGN STRUCTURE INCORPORATING SEMICONDUCTOR DEVICE STRUCTURES THAT SHIELD A BOND PAD FROM ELECTRICAL NOISE

as set forth in United States Patent Application executed inventor signature below, and further identified by <b>Attorn</b>	ey Docket Number BUR	1920070072US2
(select one) $oxtimes$ executed concurrently herewith $oxtimes$ $oxtimes$	erial No	_ Filed on
for and to said United States Patent Application including any and all Letters Patent of the United States and foreig which may issue on any such application or for said inver- extensions thereof, to be held and enjoyed by, its succes term or terms for which any and all such Letters Patent no and enjoyed by the undersigned had this Assignment no	n patents and all rights of ntion therein disclosed, in sors, legal representative nay be granted as fully an	f priority to be obtained therefor cluding any and all reissues or is and assigns to the full end of the

Each undersigned inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to IBM, its successors and assigns, in accordance herewith;

Each undersigned inventor warrants and covenants that he/she has the full and unencumbered right to sell and assign the interests hereby sold and assigned and that he/she has not executed and will not execute any document or instrument in conflict herewith:

Each undersigned inventor further covenants and agrees that he/she, upon the request and at the expense of the IBM, will execute and deliver any papers, make all rightful oaths, testify in any legal proceeding relating to said inventions and improvements, communicate to the IBM all facts known to the undersigned relating to such inventions and improvements and the history thereof; and perform all other lawful acts deemed necessary or desirable by IBM, and its legal representatives, to secure, maintain, and enforce patent protection for such inventions and improvements and for vesting title to such inventions and improvements in the IBM, and in particular to perfect title to said above-identified certain inventions, and applications including divisions and continuations thereof, and any and all Letters Patent which may be granted therefor or thereon, including reissues, extensions, or counterparts;

Each undersigned inventor hereby grants the IBM and the firm of the power to insert in this Assignment any further identification which may be necessary or desirable for recordation of this Assignment.

This assignment is governed by the substantive laws of the state of New York.

		Executed by Inventor 1 of 5	
Signature: _	David & Collins	Date:	10/9/2007
_	(David S. Collins)		•
Signature: _	MAG	Executed by Inventor 2 of 5  Date:	10/10/2007
Signature: _	Edwurd Jester (Edwarg J. Gordon)	Executed by Inventor 3 of 5  Date:	10/10/2007
	-	Executed by Inventor 4 of 5	
Signature:_	(Robert Groves)	Date:	
Signature:	Roll al	Executed by Inventor 5 of 5	109/2007
	(Robert M. Rassel)	7	'/

DOCKET NO. BUR920070072US2

#### PATENT ASSIGNMENT FORM

For and in consideration of good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor acknowledges his/her prior and ongoing obligation to sell, assign, and transfer, and agrees to sell, assign, and transfer the entire world wide right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements conceived during and within the scope of his/her employment, and further acknowledges that he/she has sold, assigned, and transferred, and hereby sells, assigns, and transfers, unto:

INTERNATIONAL BUSINESS MACHINES CORPORATION ("IBM"),
Armonk, New York 10504

a corporation of New York, and IBM desires to acquire all right, title, and interest, in and to the certain inventions (identified below), applications, and any United States and foreign patents to be obtained therefor relating to:

Title of Invention for United States Patent DESIGN STRUCTURE INCORPORATING SEMICONDUCTOR DEVICE STRUCTURES THAT SHIELD A BOND PAD FROM ELECTRICAL NOISE

as set forth in United States Patent Application execute		
inventor signature below, and further identified by Atto		20070072US2
(select one) 🛛 executed concurrently herewith <b>or</b> 🗌	Serial No	Filed on

for and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters. Patent of the United States and foreign patents and all rights of priority to be obtained therefor which may issue on any such application or for said invention therein disclosed, including any and all reissues or extensions thereof, to be held and enjoyed by, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each undersigned inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to IBM, its successors and assigns, in accordance herewith;

Each undersigned inventor warrants and covenants that he/she has the full and unencumbered right to sell and assign the interests hereby sold and assigned and that he/she has not executed and will not execute any document or instrument in conflict herewith:

Each undersigned inventor further covenants and agrees that he/she, upon the request and at the expense of the IBM, will execute and deliver any papers, make all rightful oaths, testify in any legal proceeding relating to said inventions and improvements, communicate to the IBM all facts known to the undersigned relating to such inventions and improvements and the history thereof; and perform all other lawful acts deemed necessary or desirable by IBM, and its legal representatives, to secure, maintain, and enforce patent protection for such inventions and improvements and for vesting title to such inventions and improvements in the IBM, and in particular to perfect title to said above-identified certain inventions, and applications including divisions and continuations thereof, and any and all Letters Patent which may be granted therefor or thereon, including reissues, extensions, or counterparts;

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#### DOCKET NO. BUR920070072US2

		Exec	uted by Inventor 1 of 5		
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		Exec	uted by Inventor 3 of 5		
Signal	ure:(Edwa	ırd J. Gordon)	Date:		
		Exec	uted by Inventor 4 of 5		
Signat	ure: <u>Re/Z</u> (Rober	t Groves)	Date:	9-2007	
and the second s	·	·	uted by Inventor 5 of 5	inger . ·	
Signat	ure:(Rober	rt M. Rassel)	Date:		

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PATENT REEL: 020001 FRAME: 0667

**RECORDED: 10/23/2007**